

Part Number: L-819SURKCGKW

Hyper Red
Green

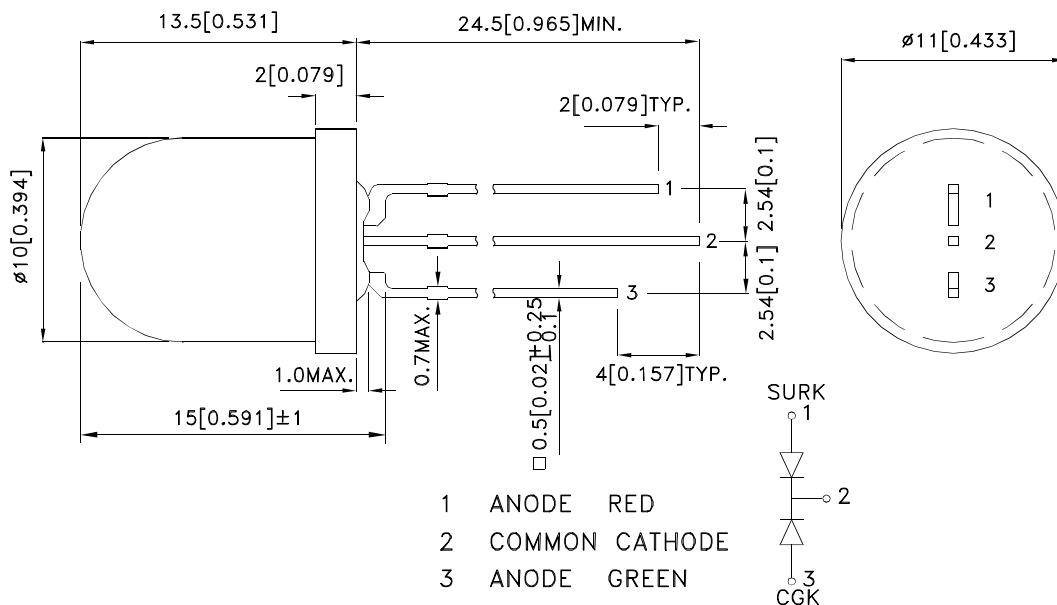
Features

- Uniform light output.
- Low power consumption.
- 3 leads with one common lead.
- Long life - solid state reliability.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GaN on GaAs substrate Light Emitting Diode.
The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 (0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-819SURKCGKW	Hyper Red (AlGaInP)	White Diffused	380	750	50°
			*120	*350	
	Green (AlGaInP)		55	130	
			*55	*130	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red Green	645 574		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red Green	28 20		nm	I _F =20mA
C	Capacitance	Hyper Red Green	35 15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red Green		10 10	uA	V _R = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

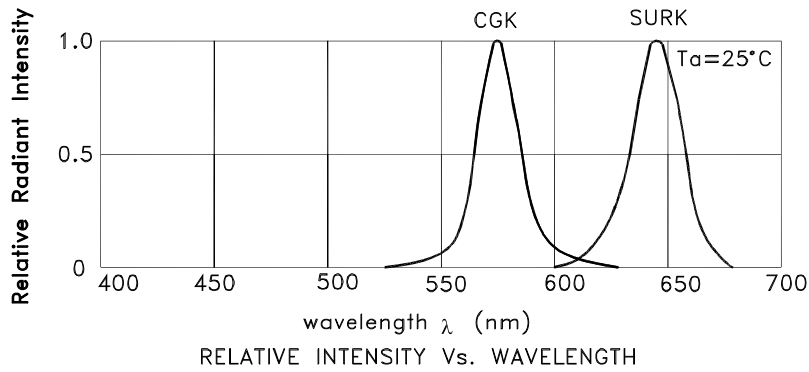
Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

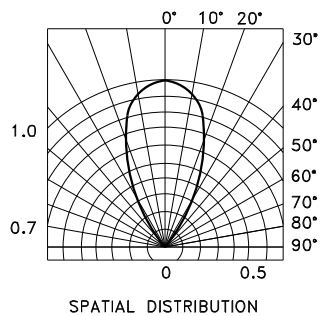
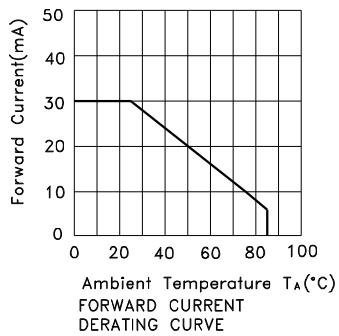
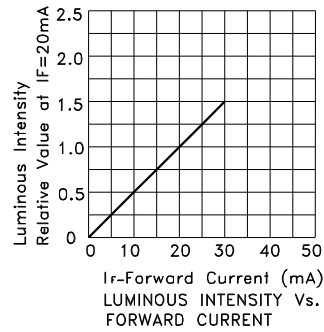
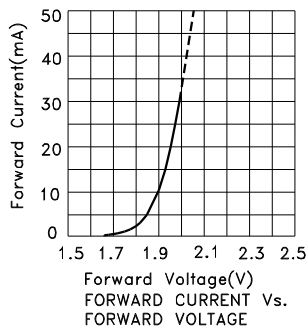
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

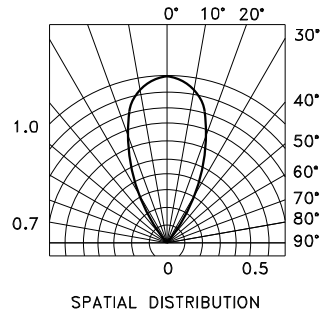
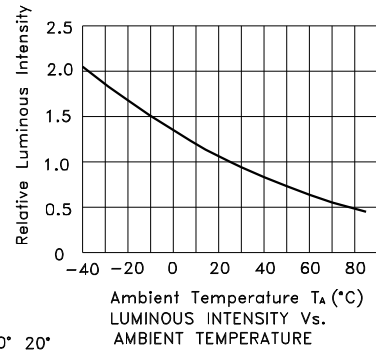
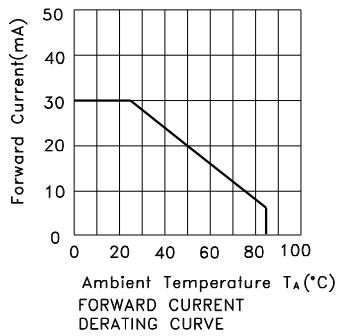
3. 5mm below package base.



L-819SURKCGKW Hyper Red

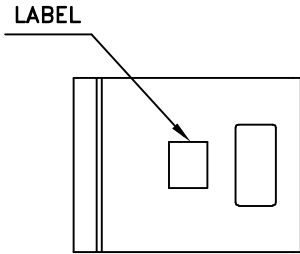
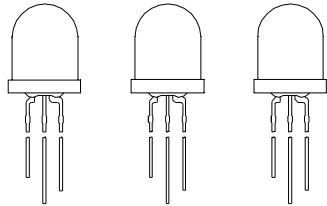


Green



PACKING & LABEL SPECIFICATIONS

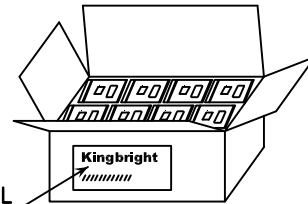
L-819SURKCGKW



200PCS / BAG



OUTSIDE LABEL



OUTSIDE LABEL

8K / 9# BOX

4K / 5# BOX

<h2 style="margin: 0;">Kingbright</h2>	
P/NO: L-819xxx	
QTY: 200 pcs	Q.C.
S/N: XXXX	<div style="border: 1px solid black; border-radius: 50%; padding: 5px; display: inline-block;"> Q C XX XX XXXX PASSED </div>
CODE: XXX	
LOT NO:	
<small>xxxxxxxxxxxxxxxxxxxxxxxx</small> RoHS Compliant	

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

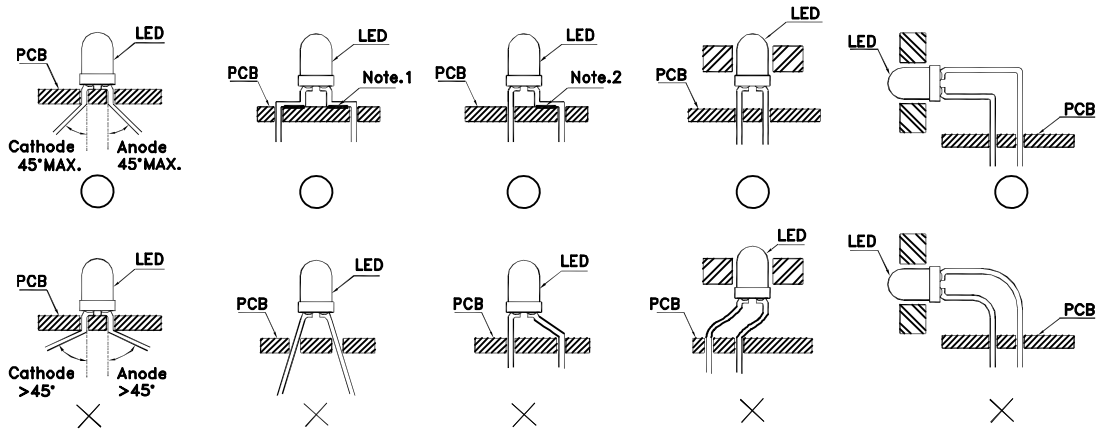


Fig.1

”O” Correct mounting method ”X” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

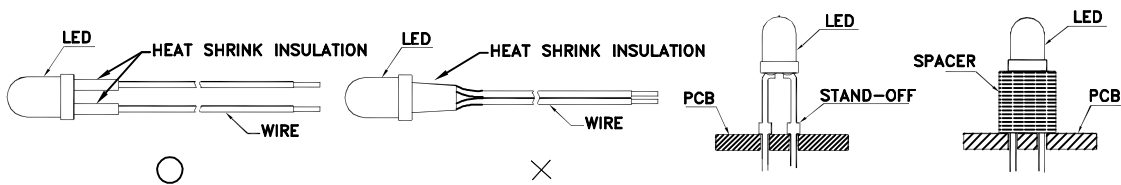


Fig. 2

Fig. 3

Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)

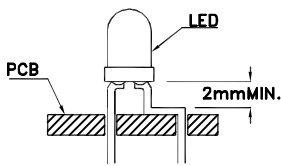


Fig. 5

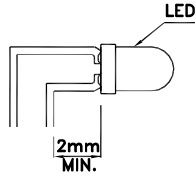


Fig. 6

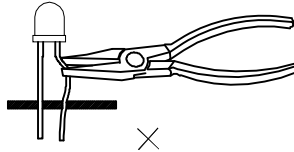


Fig. 7

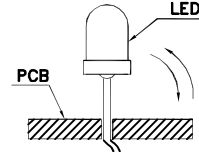
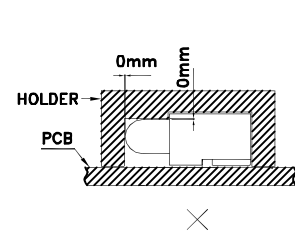
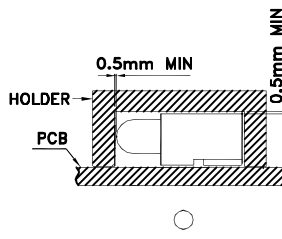
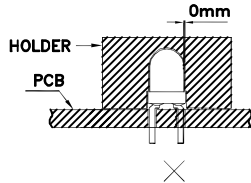
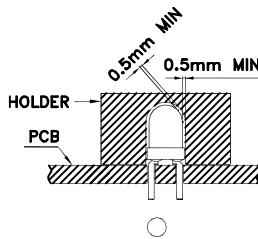


Fig. 8

7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

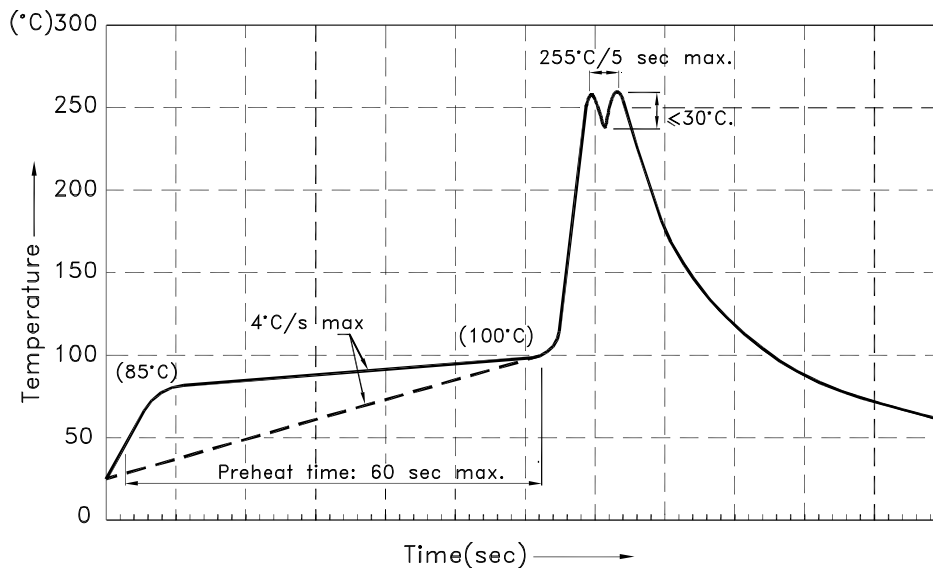


8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Detailed application notes are listed on our website.

http://www.kingbright.com/application_notes